



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 57196
Application ID: 10686486
Title of Invention: APPARATUS FOR ELECTRO
CHEMICAL DEPOSITION OF
COPPER METALLIZATION WITH
THE CAPABILITY OF IN-SITU
THERMAL ANNEALING
First Named Inventor: ROBIN CHEUNG
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-10-15
Effective Receipt Date: 2004-03-16
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8014
Attorney Docket Number: AMAT3421C2
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 200782
Deposit Account Name: N. ALEXANDER NOLTE
Access Code: ****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-03-16
RAM Sequence Number: 17




Digital Certificate Holder: cn=N. Alexander Nolte,ou=Registered Attorneys,ou=Patent and
Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: e94b3301e9e0ed755aee8d4d3aed3395c1a2fe3b

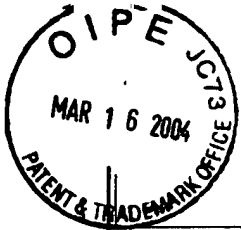


TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

| Title of Invention | APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING | | | | | | | | | | | | | | | |
|--|--|----------------|---------------------------|-------------|----------------|--|----------------------|------------------|--|------------------|--------|---------------------------|--|------------|--|------------|
| Application Number: 10/686486  | | | | | | | | | | | | | | | | |
| Date: 2003-10-15 | | | | | | | | | | | | | | | | |
| First Named Applicant: ROBIN CHEUNG | | | | | | | | | | | | | | | | |
| Confirmation Number: 8014 | | | | | | | | | | | | | | | | |
| Attorney Docket Number: AMAT3421C2 | | | | | | | | | | | | | | | | |
| <p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p> | | | | | | | | | | | | | | | | |
| <table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mr. N. ALEXANDER NOLTE Registered Number: 45689</td><td>[N. ALEXANDER NOLTE]</td><td>Attorney</td></tr></tbody></table> | | | Submitted by: | Elec. Sign. | Sign. Capacity | Mr. N. ALEXANDER NOLTE Registered Number: 45689 | [N. ALEXANDER NOLTE] | Attorney | | | | | | | | |
| Submitted by: | Elec. Sign. | Sign. Capacity | | | | | | | | | | | | | | |
| Mr. N. ALEXANDER NOLTE Registered Number: 45689 | [N. ALEXANDER NOLTE] | Attorney | | | | | | | | | | | | | | |
| <table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-fee-sheet</td><td>AMAT3421C2NAN2-usfees.xml</td></tr><tr><td></td><td>us-fee-sheet.xsl</td></tr><tr><td></td><td>us-fee-sheet.dtd</td></tr><tr><td>us-ids</td><td>AMAT3421C2NAN2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table> | | | Documents being submitted | Files | us-fee-sheet | AMAT3421C2NAN2-usfees.xml | | us-fee-sheet.xsl | | us-fee-sheet.dtd | us-ids | AMAT3421C2NAN2-usidst.xml | | us-ids.dtd | | us-ids.xsl |
| Documents being submitted | Files | | | | | | | | | | | | | | | |
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| | us-ids.dtd | | | | | | | | | | | | | | | |
| | us-ids.xsl | | | | | | | | | | | | | | | |



Comments

NO FEES REQUIRED - FILED BEFORE THE FIRST OA. - IDS 3 OF 3.



FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

| Title of Invention | APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING | | | | | | | | | | |
|--|--|-----------|-------------|-----------------|----------|-----------|-------------|---|------|-----|-----|
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| First Named Applicant: ROBIN CHEUNG | | | | | | | | | | | |
| Attorney Docket Number: AMAT3421C2 | | | | | | | | | | | |
| Art Unit: 1753 | | | | | | | | | | | |
| TOTAL FEE AUTHORIZED \$180 | | | | | | | | | | | |
| Patent fees are subject to annual revisions on or about October 1st of each year. | | | | | | | | | | | |
| BASIC FILING FEE | | | | | | | | | | | |
| <table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table> | | | | Fee Description | Fee Code | Amount \$ | Fee Paid \$ | Submission Of Information Disclosure Stmt Fee | 1806 | 180 | 180 |
| Fee Description | Fee Code | Amount \$ | Fee Paid \$ | | | | | | | | |
| Submission Of Information Disclosure Stmt Fee | 1806 | 180 | 180 | | | | | | | | |
| AUTHORIZED BILLING INFORMATION | | | | | | | | | | | |
| The commissioner is hereby authorized to charge indicated fees and credit any overpayments to: | | | | | | | | | | | |
| Deposit account number: 200782 | | | | | | | | | | | |
| Access Code ***** | | | | | | | | | | | |
| Deposit name: MOSER PATTERSON SHERIDAN | | | | | | | | | | | |
| Deposit authorized name: N. ALEXANDER NOLTE | | | | | | | | | | | |
| Signature: \N. ALEXANDER NOLTE\ | | | | | | | | | | | |
| Date (YYYYMMDD): 2004-03-16 | | | | | | | | | | | |



FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

| Title of Invention | APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING | | | | | | | | | | |
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| Application Number: 10/686486  | | | | | | | | | | | |
| Date: 2003-10-15 | | | | | | | | | | | |
| First Named Applicant: ROBIN CHEUNG | | | | | | | | | | | |
| Attorney Docket Number: AMAT3421C2 | | | | | | | | | | | |
| Art Unit: 1753 | | | | | | | | | | | |
| TOTAL FEE AUTHORIZED \$180 | | | | | | | | | | | |
| Patent fees are subject to annual revisions on or about October 1st of each year. | | | | | | | | | | | |
| BASIC FILING FEE | | | | | | | | | | | |
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| Submission Of Information Disclosure Stmt Fee | 1806 | 180 | 180 | | | | | | | | |
| AUTHORIZED BILLING INFORMATION | | | | | | | | | | | |
| The commissioner is hereby authorized to charge indicated fees and credit any overpayments to: | | | | | | | | | | | |
| Deposit account number: 200782 | | | | | | | | | | | |
| Access Code: **** | | | | | | | | | | | |
| Deposit name: MOSER PATTERSON SHERIDAN | | | | | | | | | | | |
| Deposit authorized name: N. ALEXANDER NOLTE | | | | | | | | | | | |
| Signature: \N. ALEXANDER NOLTE\ | | | | | | | | | | | |
| Date (YYYYMMDD): 2004-03-16 | | | | | | | | | | | |



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF
COPPER METALLIZATION WITH THE CAPABILITY OF IN-
SITU THERMAL ANNEALING

Application Number: 10/686486



Confirmation Number: 8014

First Named Applicant: ROBIN CHEUNG

Attorney Docket Number: AMAT3421C2

Art Unit: 1753

Search string: (5252807 or 5256274 or 5259407 or 5290361
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US Patent Documents

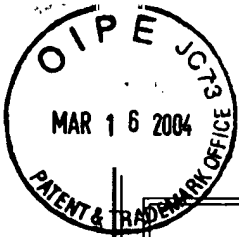
Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass |
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| 43 | 6309520 | 2001-10-30 | WOODRUFF, ET AL. |
| 44 | 6508920 | 2003-01-21 | RITZDORF, ET AL. |

Signature



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|---------------|------|
| Examiner Name | Date |
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